

Application Serial No: 10/580,157

Responsive to the Office Action mailed on: November 27, 2007

IN THE SPECIFICATION**RECEIVED
CENTRAL FAX CENTER****APR 24 2008****Amendments to the Specification:**

Please amend the following at page 9, line 26-page 10, line 4 of the specification:

Fig. 4 illustrates a circuit board A3 according to a third embodiment of the present invention. In the present embodiment, the bottom portion of the metal member 3 is partly removed through an etching process to form a recess 3c. Further in the present embodiment, the metal member 3 is bonded to one pad 4a via one ~~sold~~solid layer 6. The ~~sold~~solid layer 6 covers the entire upper surface of the pad 4a.